

SPECIFICATION



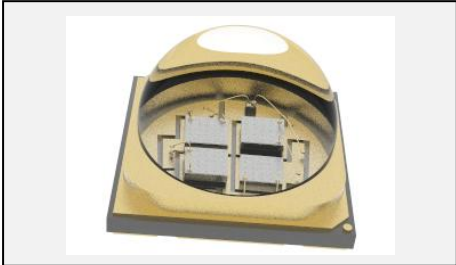
Contents

1. Description



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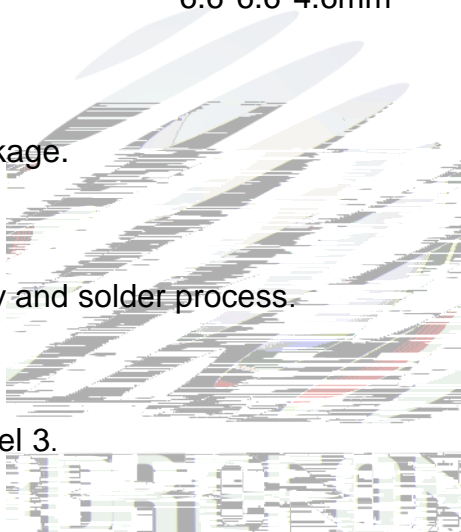
1.1 General Description



This production use the ceramics and quartz lens package outline size 6.6*6.6*4.6mm
6.6*6.6*4.6mm

1.2 Features

- ▶ Ceramic and quartz lens package.
- ▶ Viewing angle:60.
- ▶ Suitable for all SMT assembly and solder process.
- ▶ Available on tape and reel.
- ▶ Moisture sensitivity level: Level 3.
- ▶ RoHS compliant.



1.3 Application

- ▶ UV Curing.
- ▶ UV Ink Curing.
- ▶ Ultraviolet disinfection.
- ▶ General use.

1.4 Package Dimension

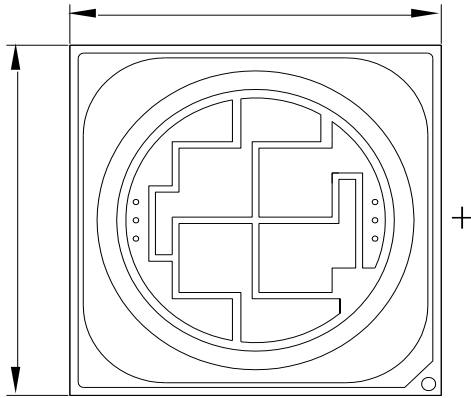


Fig.1-1 Top view

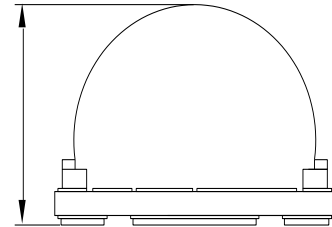


Fig.1-2 Side view

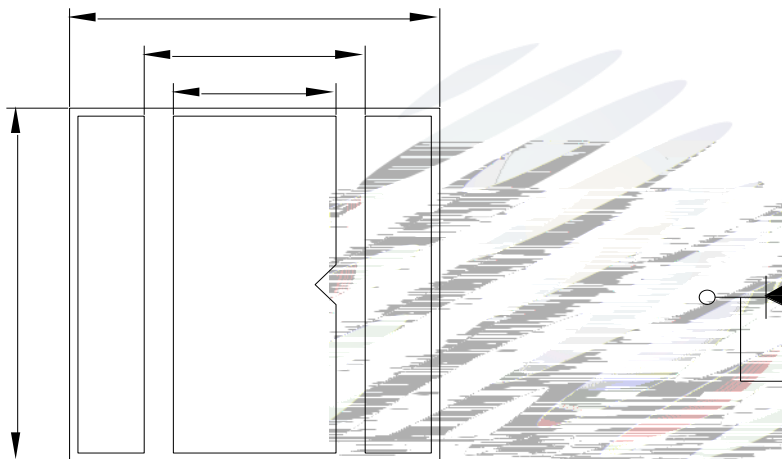


Fig.1-3 Bottom view

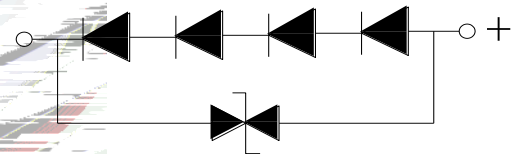


Fig.1-4 Polarity

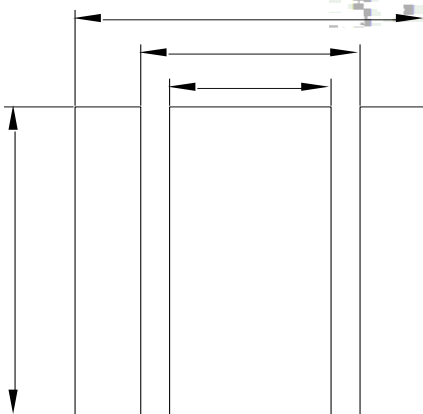


Fig.1-5 Soldering patterns

Notes

All dimensions units are millimeters.

All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Code	Value			Unit
				Min.	Typ	Max.	
Forward Voltage	V_F	$I_F=700\text{mA}$	D04	12.8	---	13.6	V
			D05	13.6	---	14.4	
			D06	14.4	---	15.2	
Reverse Current	I_R	$V_R=20\text{V}$	---	---	---	5	μA
Total radiant flux RF-C65S6-UBP-AR-04 (365-370nm)	Φ_e	$I_F=700\text{mA}$	1B42	3550	---	4500	mW
			1B43	4500	5200	6300	
			1B44	6300	---	7100	
Total radiant flux RF-C65S6-UEP-AR-04 (380-390nm)	Φ_e	$I_F=700\text{mA}$	1B42	3550	---	4500	mW
			1B43	4500	5800	6300	
			1B44	6300	---	7100	
Total radiant flux RF-C65S6-UGP-AR-04 (390-400nm)	Φ_e	$I_F=700\text{mA}$	1B42	3550	---	4500	mW
			1B43	4500	5800	6300	
			1B44	6300	---	7100	
Total radiant flux RF-C65S6-UIP-AR-04 (400-410nm)	Φ_e	$I_F=700\text{mA}$	1B42	3550	---	4500	mW
			1B43	4500	5800	6300	
			1B44	6300	---	7100	
Viewing Angle	2 θ 1/2	$I_F=700\text{mA}$		---	60	---	deg
Thermal Resistance.	R_{THJ-S}	$I_F=700\text{mA}$		---	4.5	---	$^{\circ}\text{C}/\text{W}$

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Notes

1. 1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$.
3. The above wavelength measurement allowance tolerance is $\pm 2nm$.
4. The above radiation flux measurement allowance tolerance $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

1.6 Typical optical characteristics curves

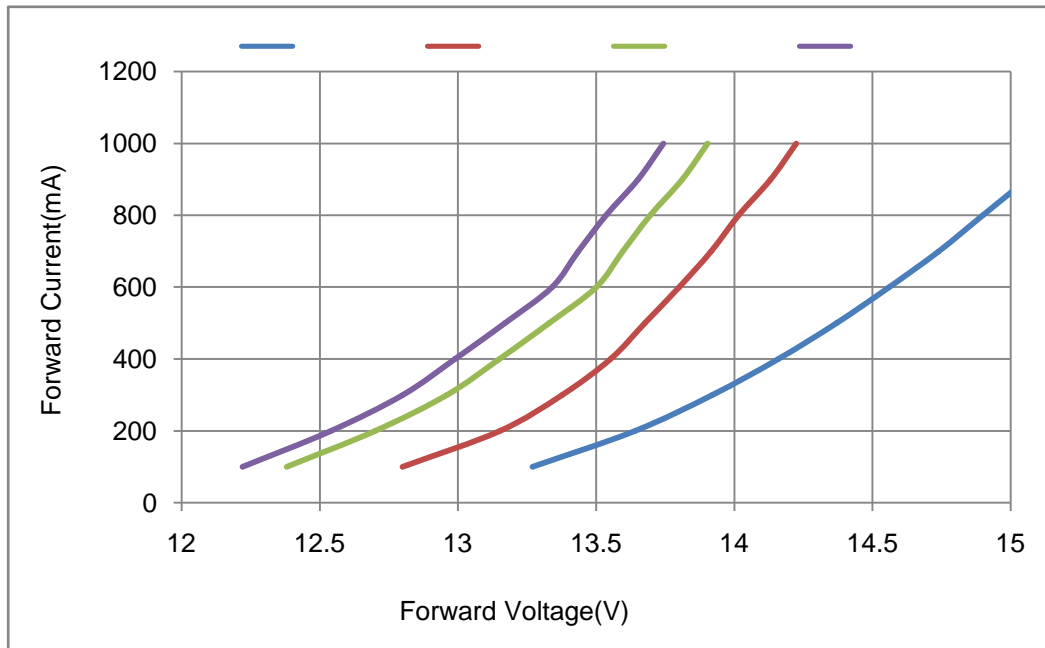


Fig.1- Forward Voltage Vs. Forward Current

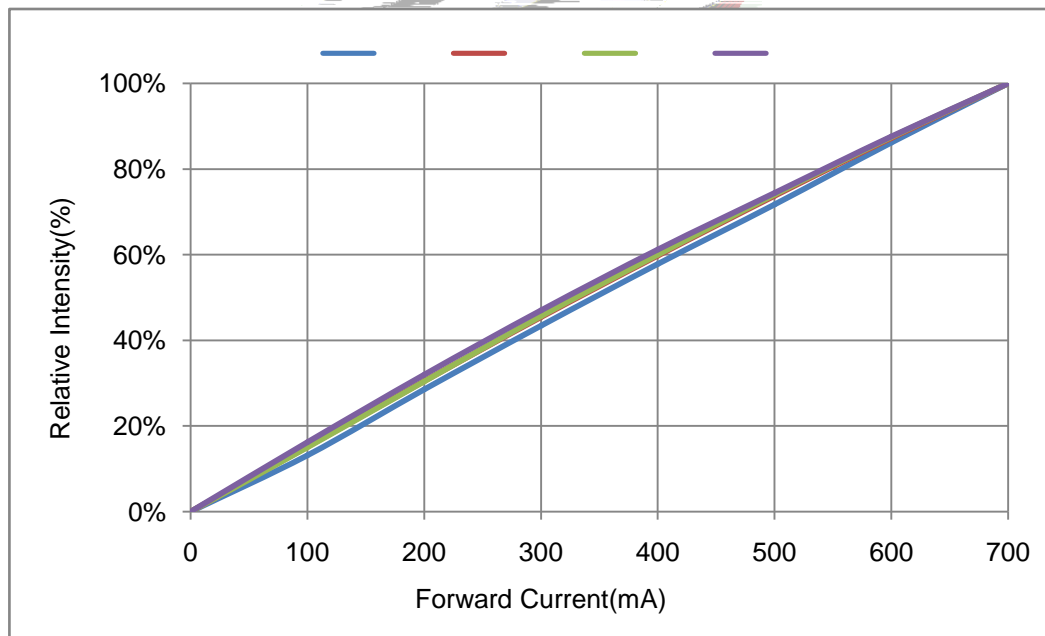


Fig.2- Forward Current Vs. Relative Power

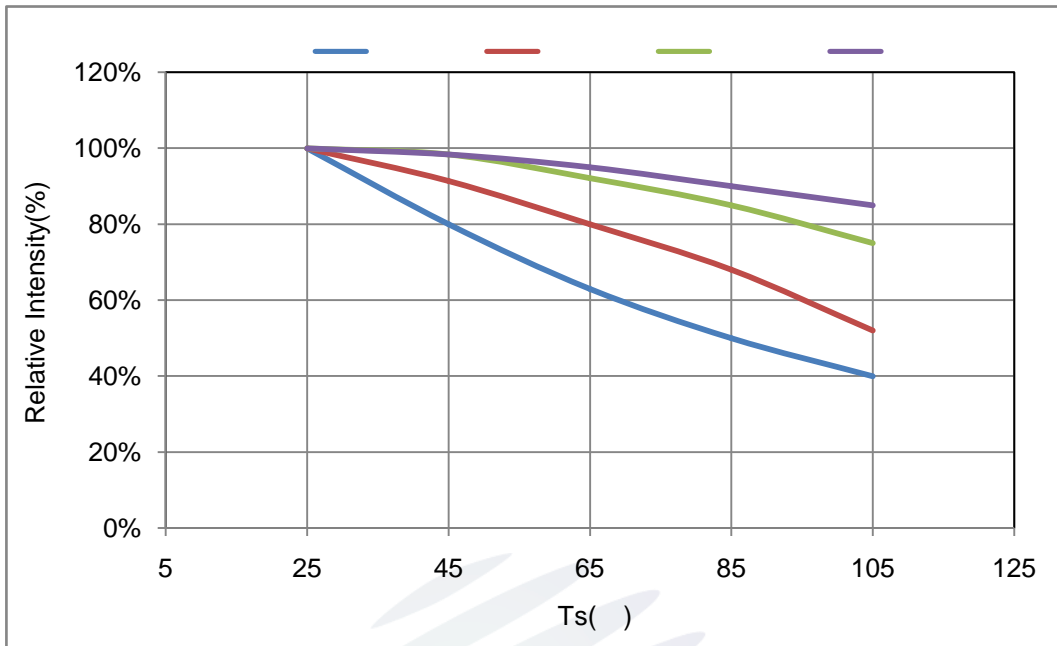


Fig.3-Solder Temperature VS. Relative Power

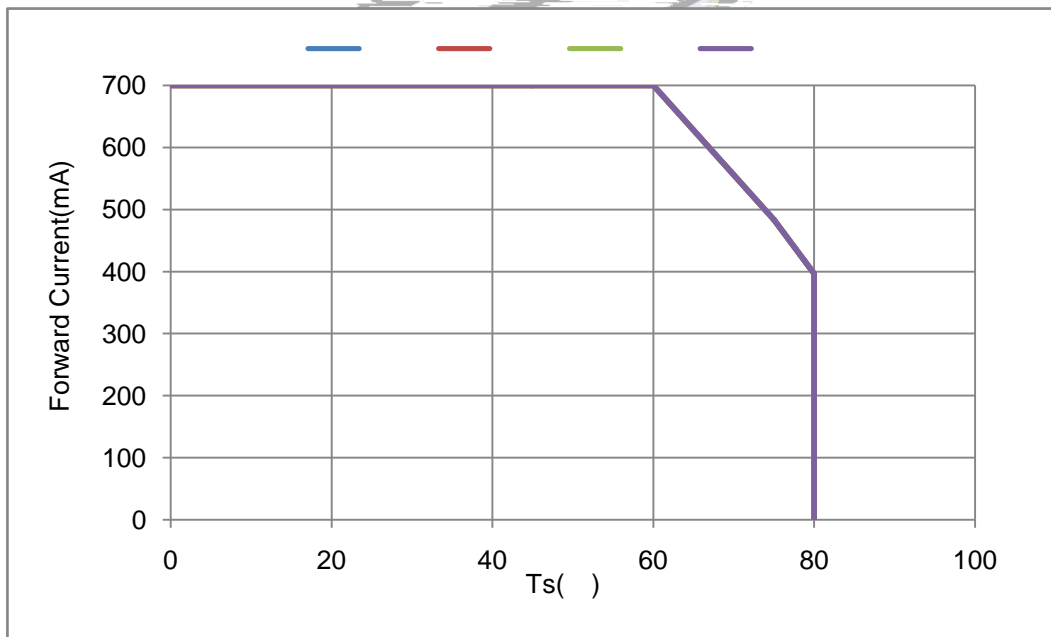


Fig.4-Ts Temperature VS. Forward Current

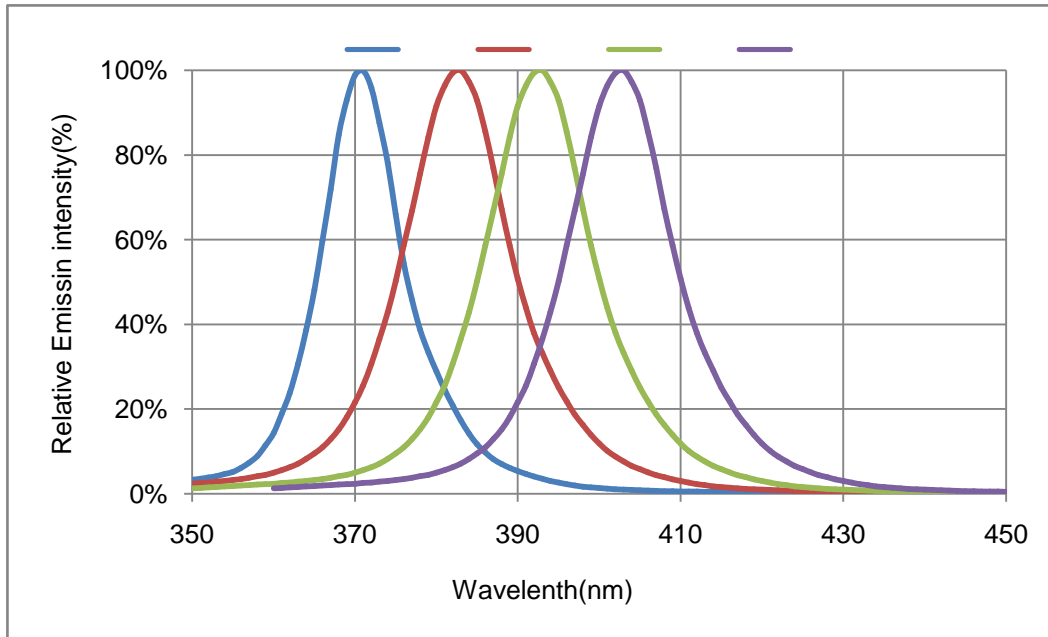


Fig.5-Spectrum Distribution

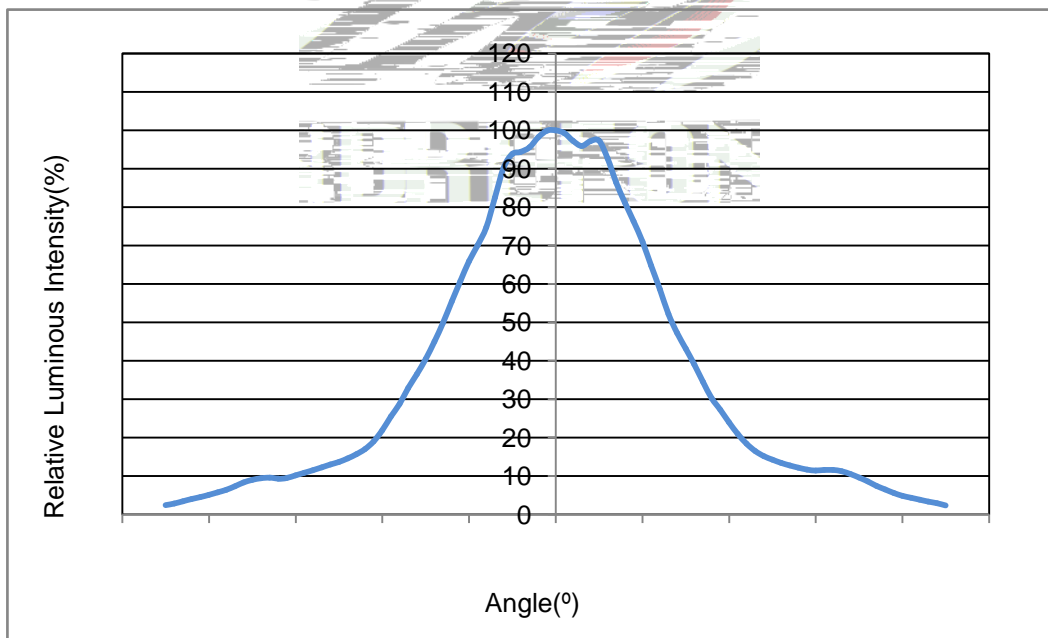


Fig.6- Radiation Diagram



2.1.3



2.3 Cardboard Box

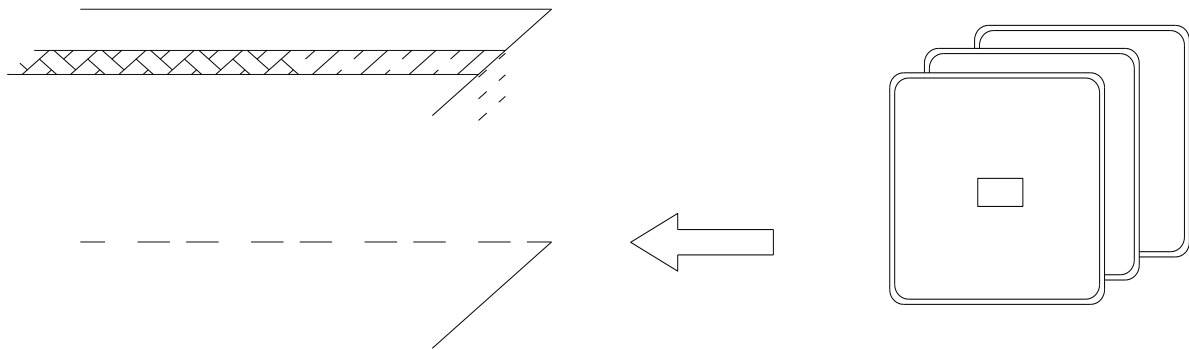


Fig.2-5 Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re
Reflow	JESD22-B106	Temp:260 max T=10 sec	3times.	10Pcs.	0/1
Thermal Shock	JESD22-A106	-40 15min ↑↓10s 100 15min	100 Cycles	10Pcs.	0/1
Life Test	JESD22-A108	T _a =25 I _F =700mA	1000Hrs.	10Pcs.	0/1



3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1 SMT Reflow Soldering Instructions SMT

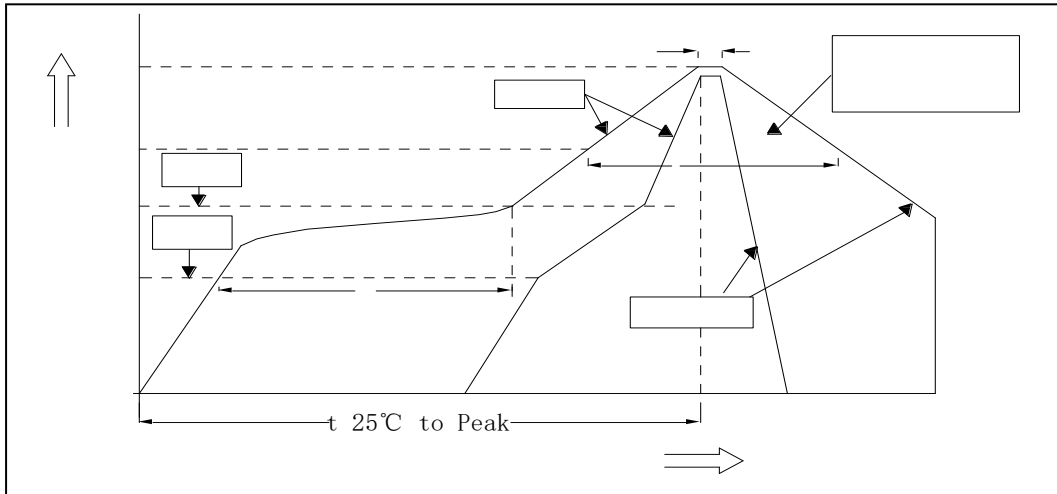


Fig.3-1 SMT Reflow Soldering Instructions

Table 3-1 SMT Reflow Soldering Instructions

Average temperature rise speed	T_{smax} T_P	Max 3 °C/ s	3 °C/
Preheating: minimum temperature	(T_{smin})	150 °C	
Preheating: Max temperature	(T_{smax})	200 °C	
Preheating: Time	T_{smin} T_{smax}	60s-120s	60 - 120
Time limited to maintain high temperature: the temperature	(T_L)	217 °C	
Time limited to maintain high temperature: The Time	(t_L)	Max 60s	60
Peak /Classification of temperature:	/ (T_P)	260 °C	
Time limit classification of peak temperature time	t_p	Max 10s	10
Hold time within 5 °C with the actual peak temperature (T_P)	(T_P) 5 °C	Max 30s	30
Cooling speed		Max 6 °C/ s	6 °C/
Needed time from 25 °C to T_p	25 °C	Max 8 minutes	8

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged.

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

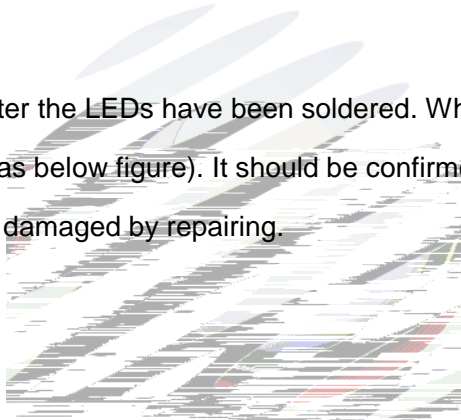
(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED



3.1.3 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.





Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	24hours 24
Baking		60 5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 65 5 for above 24 hours.

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(10) When using this product, you need to take good care to prevent it from causing harm to eyes and human body.

(11) Other points for attention, please refer to our relevant information.



Declare

This specification is written both in English and in Chinese and the latter is formal.